

ELECTRICAL / OPTICAL CHARACTERISTICS at T_A=25°C

Parameter	Symbol	Emitting Color	Value		Unit
Farameter	Symbol	Emitting Color	Тур.	p. Max.	Ullit
Wavelength at Peak Emission I _F = 20mA	λ_{peak}	Super Bright Orange	610	-	nm
Dominant Wavelength I _F = 20mA	λ _{dom} ^[1]	Super Bright Orange	605	-	nm
Spectral Bandwidth at 50% Φ REL MAX I _F = 20mA	Δλ	Super Bright Orange	29	-	nm
Capacitance	С	Super Bright Orange	15	-	pF
Forward Voltage I _F = 20mA	V _F ^[2]	Super Bright Orange	2.1	2.5	V
Reverse Current (V _R = 5V)	I _R	Super Bright Orange	-	10	μА
Temperature Coefficient of λ_{peak} $I_F=20mA, -10^{\circ}C \leq T \leq 85^{\circ}C$	$TC_{\lambda peak}$	Super Bright Orange	0.13	-	nm/°C
Temperature Coefficient of λ_{dom} I_F = 20mA, -10°C $\leq T \leq 85^{\circ}C$	TC_{\lambdadom}	Super Bright Orange	0.06	-	nm/°C
Temperature Coefficient of V_F I_F = 20mA, -10°C \leq T \leq 85°C	TC _V	Super Bright Orange	-1.9	-	mV/°C

Notes:

ABSOLUTE MAXIMUM RATINGS at $T_A=25$ °C

Parameter	Symbol	Value	Unit
Power Dissipation	P _D	75	mW
Reverse Voltage	V_R	5	V
Junction Temperature	T _j	115	°C
Operating Temperature	T _{op}	-40 to +85	°C
Storage Temperature	T _{stg}	-40 to +85	°C
DC Forward Current	I _F	30	mA
Peak Forward Current	I _{FM} ^[1]	195	mA
Electrostatic Discharge Threshold (HBM)	-	3000	V
Thermal Resistance (Junction / Ambient)	R _{th JA} ^[2]	680	°C/W
Thermal Resistance (Junction / Solder point)	R _{th JS} ^[2]	500	°C/W

Notes:
1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. $R_{h, M}$, $R_{h, M}$, $R_{h, M}$ Results from mounting on PC board FR4 (pad size \geq 16 mm² per pad).
3. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.



Notes:

1. The dominant wavelength (λd) above is the setup value of the sorting machine. (Tolerance λd:±1nm.)

2. Forward voltage: ±0.1V.

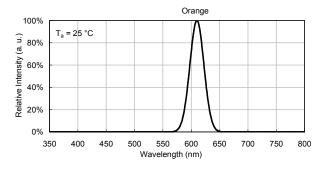
3. Wavelength value is traceable to CIE127-2007 standards.

4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

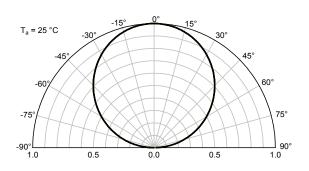


TECHNICAL DATA

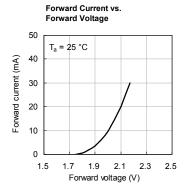
RELATIVE INTENSITY vs. WAVELENGTH

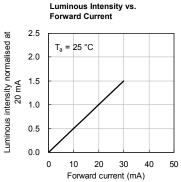


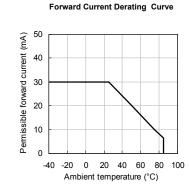
SPATIAL DISTRIBUTION

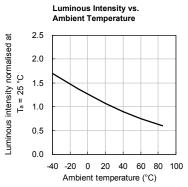


SUPER BRIGHT ORANGE

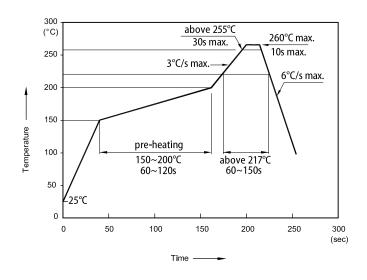






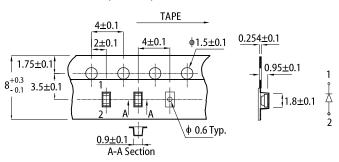


REFLOW SOLDERING PROFILE for LEAD-FREE SMD PROCESS

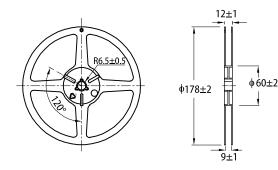


- 1. Don't cause stress to the LEDs while it is exposed to high temperature.
 2. The maximum number of reflow soldering passes is 2 times.
 3. Reflow soldering is recommended. Other soldering methods are not recommended as they might cause damage to the product

TAPE SPECIFICATIONS (units: mm)

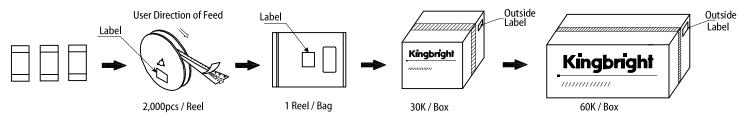


REEL DIMENSION (units: mm)





PACKING & LABEL SPECIFICATIONS





PRECAUTIONARY NOTES

- The information included in this document reflects representative usage scenarios and is intended for technical reference only.
- The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
- When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If customer usage exceeds the specified limits, Kingbright will not be responsible for any subsequent issues.

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